



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
EXPEDITED PROCEDURE PURSUANT
TO 37 CFR §1.116 REQUESTED
Attn: BOX AF

09/809,181
503.39864X00

#16
Response
J. Magallon
SEP 26 2002
RECEIVED
TECHNOLOGY CENTER 280C

Applicants: **T. SATOH et al.**

Application No.: **09/809,181**

Filing Date: **March 16, 2001**

Title: **SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD
FOR HIGH RELIABILITY AND PRODUCTION YIELD RATE WITH
MINIMAL DAMAGE DUE TO APPLICATION OF MECHANICAL
STRESS AND THERMAL STRESS (AS AMENDED)**

Art Unit: **2815**

Examiner: **Jose R. Diaz**

RESPONSE AFTER FINAL

Assistant Commissioner for Patents
Washington, D.C. 20231

September 23, 2002

Sir:

In response to the final Office Action (Paper No. 14) dated May 21, 2002, the following amendments and remarks are submitted in the above-identified application.

Please amend the above-identified application as follows:

REMARKS

Claims 1-10 and 28-36 are pending in this application.

Claims 1-10 and 28-36 have been rejected under 35 U.S.C. §102(b) as being anticipated by, or in the alternative, under 35 U.S.C. §103(a) as being obvious over the